



May 2001

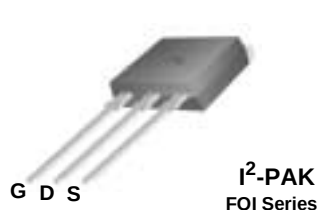
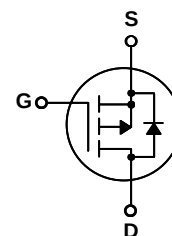
QFET™**FQB11P06 / FQI11P06****60V P-Channel MOSFET****General Description**

These P-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand a high energy pulse in the avalanche and commutation modes. These devices are well suited for low voltage applications such as automotive, DC/DC converters, and high efficiency switching for power management in portable and battery operated products.

Features

- -11.4A, -60V, $R_{DS(on)} = 0.175\Omega$ @ $V_{GS} = -10V$
- Low gate charge (typical 13 nC)
- Low C_{rss} (typical 45 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability
- 175°C maximum junction temperature rating

**Absolute Maximum Ratings** $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	FQB11P06 / FQI11P06	Units
V_{DSS}	Drain-Source Voltage	-60	V
I_D	Drain Current - Continuous ($T_C = 25^\circ\text{C}$)	-11.4	A
	- Continuous ($T_C = 100^\circ\text{C}$)	-8.05	A
I_{DM}	Drain Current - Pulsed (Note 1)	-45.6	A
V_{GSS}	Gate-Source Voltage	± 25	V
E_{AS}	Single Pulsed Avalanche Energy (Note 2)	160	mJ
I_{AR}	Avalanche Current (Note 1)	-11.4	A
E_{AR}	Repetitive Avalanche Energy (Note 1)	5.3	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	-7.0	V/ns
P_D	Power Dissipation ($T_A = 25^\circ\text{C}$) *	3.13	W
	Power Dissipation ($T_C = 25^\circ\text{C}$)	53	W
	- Derate above 25°C	0.35	W/ $^\circ\text{C}$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
T_L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	--	2.85	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *	--	40	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	--	62.5	$^\circ\text{C/W}$

* When mounted on the minimum pad size recommended (PCB Mount)

FQB11P06 / FQI11P06

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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Off Characteristics

BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = -250\text{ }\mu\text{A}$	-60	--	--	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = -250\text{ }\mu\text{A}$, Referenced to 25°C	--	-0.07	--	V/ $^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -60\text{ V}, V_{GS} = 0\text{ V}$	--	--	-1	μA
		$V_{DS} = -48\text{ V}, T_C = 150^\circ\text{C}$	--	--	-10	μA
I_{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = -25\text{ V}, V_{DS} = 0\text{ V}$	--	--	-100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = 25\text{ V}, V_{DS} = 0\text{ V}$	--	--	100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\text{ }\mu\text{A}$	-3.0	--	-5.0	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = -10\text{ V}, I_D = -5.7\text{ A}$	--	0.14	0.175	Ω
g_{FS}	Forward Transconductance	$V_{DS} = -30\text{ V}, I_D = -5.7\text{ A}$ (Note 4)	--	5.1	--	S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = -25\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$	--	420	550	pF
C_{oss}	Output Capacitance		--	195	250	pF
C_{rss}	Reverse Transfer Capacitance		--	45	60	pF

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = -30\text{ V}, I_D = -5.7\text{ A},$ $R_G = 25\text{ }\Omega$ (Note 4, 5)	--	6.5	25	ns
t_r	Turn-On Rise Time		--	40	90	ns
$t_{d(off)}$	Turn-Off Delay Time		--	15	40	ns
t_f	Turn-Off Fall Time		--	45	100	ns
Q_g	Total Gate Charge	$V_{DS} = -48\text{ V}, I_D = -11.4\text{ A},$ $V_{GS} = -10\text{ V}$ (Note 4, 5)	--	13	17	nC
Q_{gs}	Gate-Source Charge		--	2.0	--	nC
Q_{gd}	Gate-Drain Charge		--	6.3	--	nC

Drain-Source Diode Characteristics and Maximum Ratings

I _S	Maximum Continuous Drain-Source Diode Forward Current		--	--	-11.4	A
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	-45.6	A
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = -11.4 A	--	--	-4.0	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = -11.4 A,	--	83	--	ns
Q _{rr}	Reverse Recovery Charge	dI _F / dt = 100 A/μs (Note 4)	--	0.26	--	μC

Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. $L = 1.44\text{ mH}, I_{AS} = -11.4\text{ A}, V_{DD} = -25\text{ V}, R_G = 25\text{ }\Omega$, Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq -11.4\text{ A}, dI/dt \leq 300\text{ A}/\mu\text{s}, V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$
4. Pulse Test : Pulse width $\leq 300\text{ }\mu\text{s}$, Duty cycle $\leq 2\%$
5. Essentially independent of operating temperature

Typical Characteristics

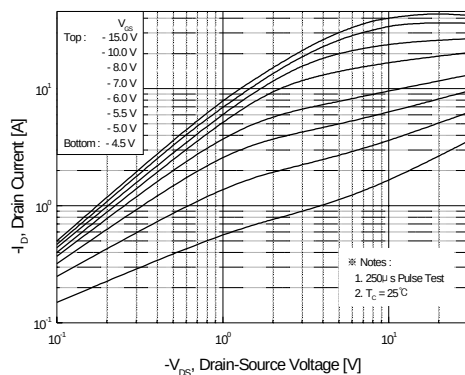


Figure 1. On-Region Characteristics

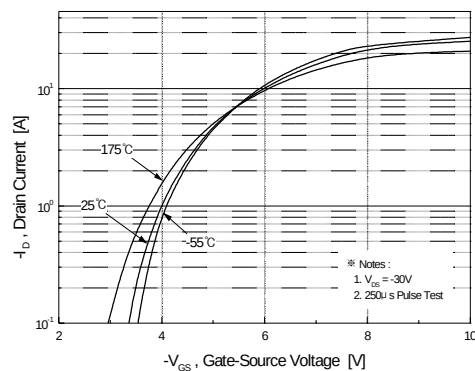


Figure 2. Transfer Characteristics

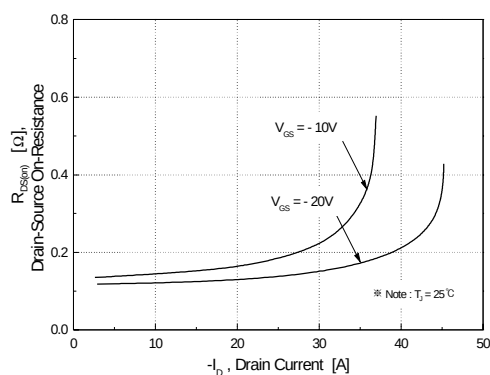


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

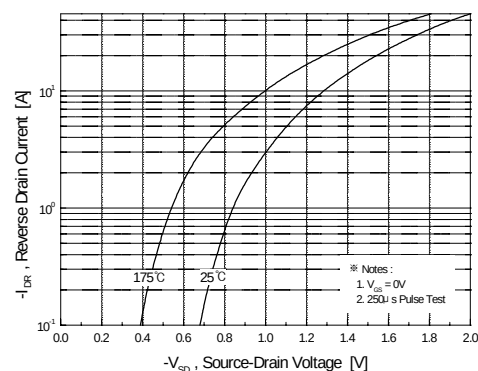


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

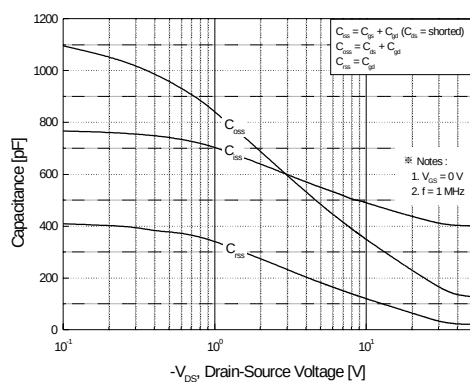


Figure 5. Capacitance Characteristics

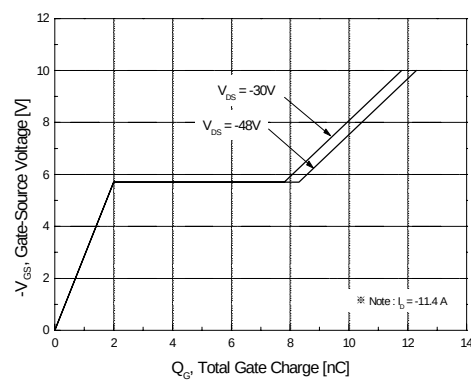


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

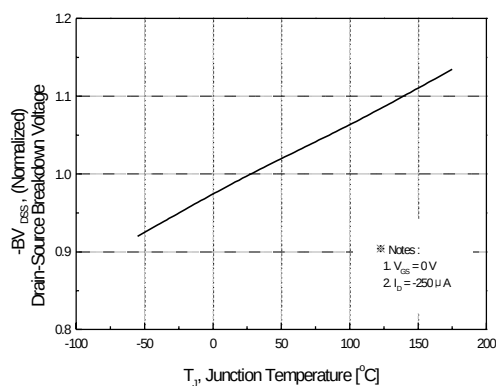


Figure 7. Breakdown Voltage Variation vs. Temperature

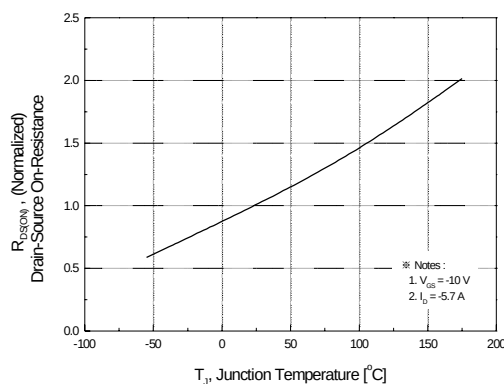


Figure 8. On-Resistance Variation vs. Temperature

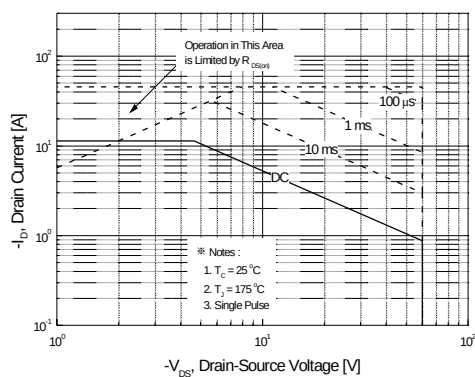


Figure 9. Maximum Safe Operating Area

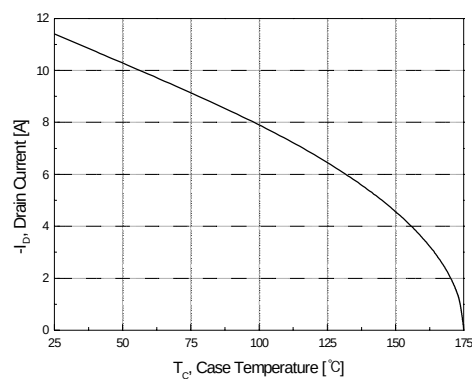


Figure 10. Maximum Drain Current vs. Case Temperature

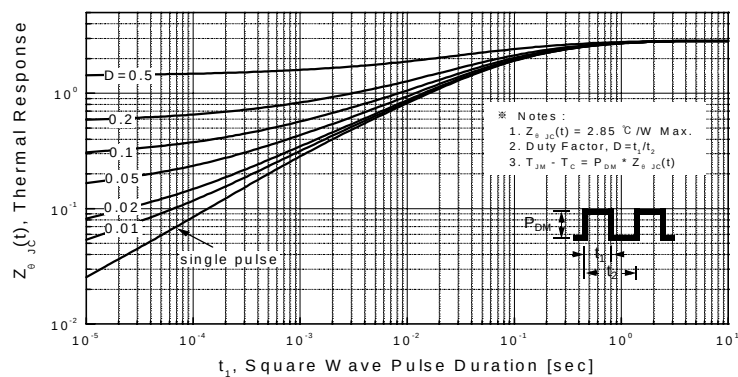
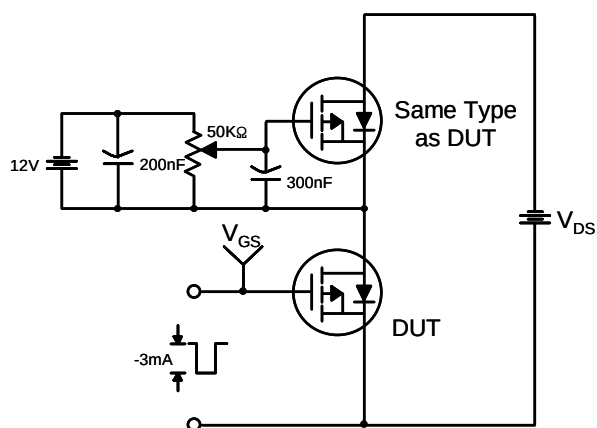
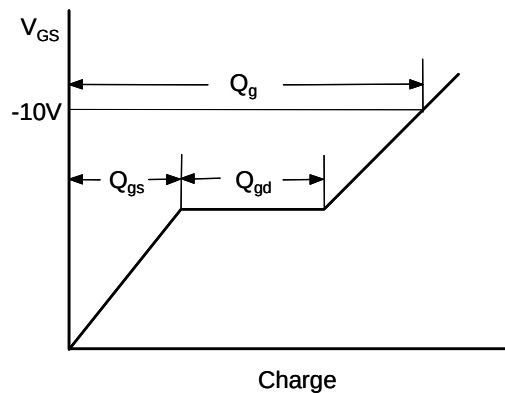
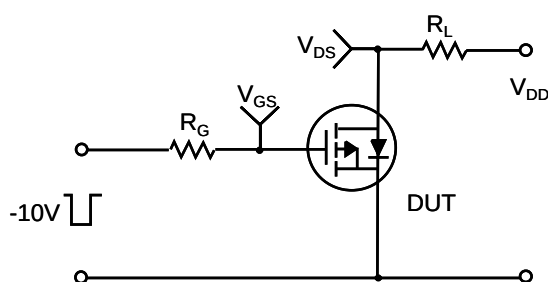
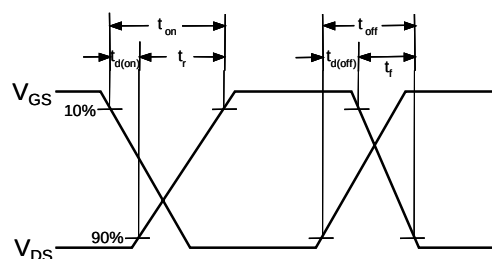


Figure 11. Transient Thermal Response Curve

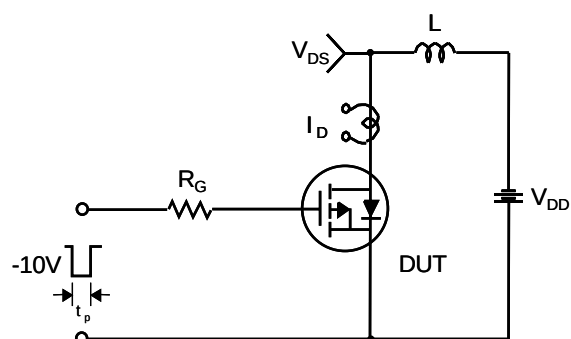
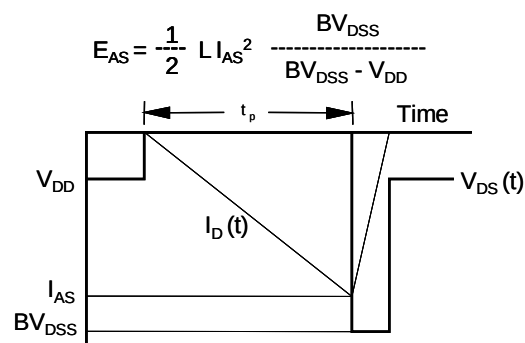
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

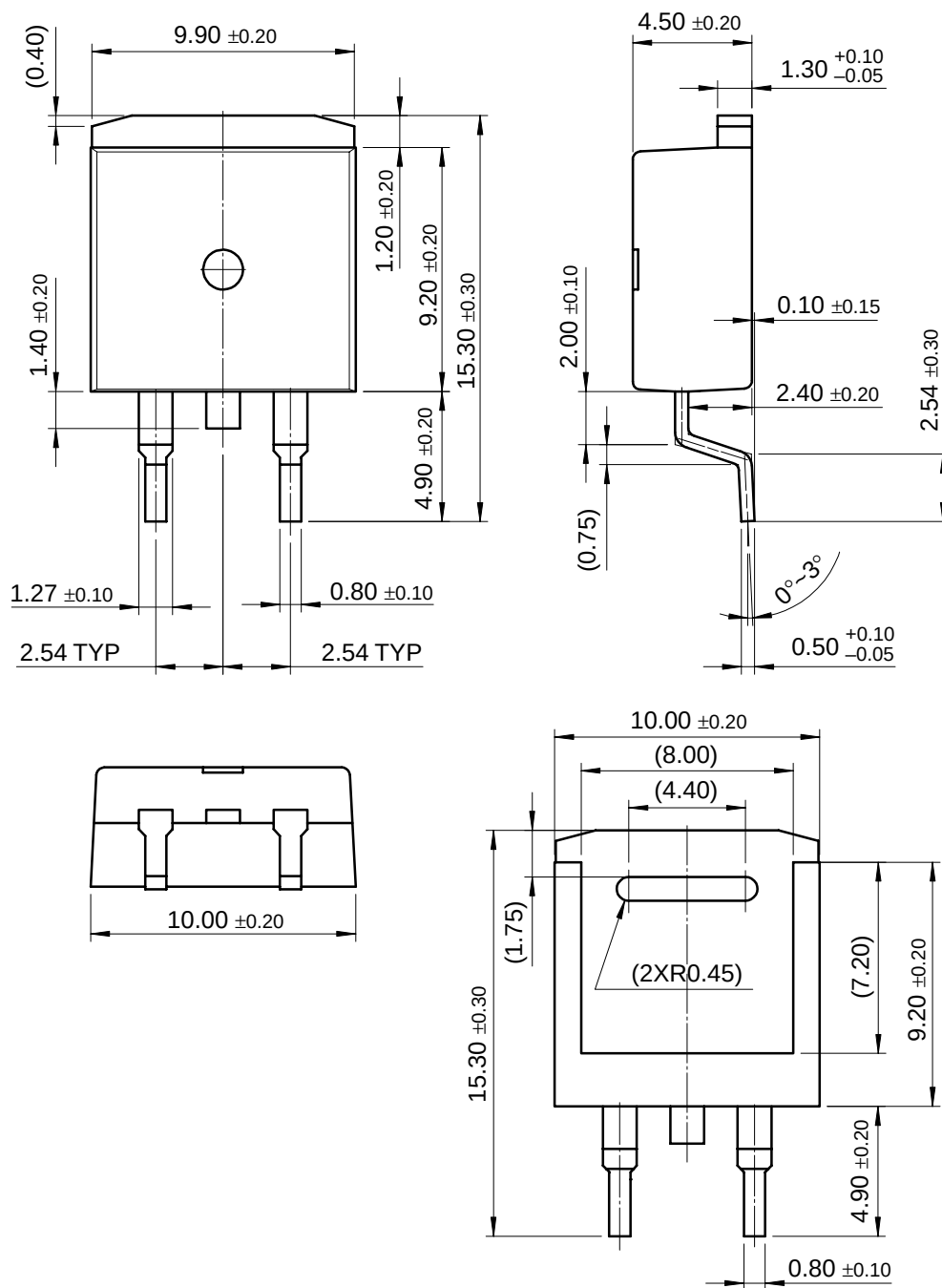


The top diagram shows a circuit for testing the body diode of a MOSFET. The MOSFET is configured with its source connected to ground and its drain connected to a load inductor L and a supply voltage V_{DD} . The gate is driven by a pulse generator V_{GS} through a resistor R_G . The MOSFET is labeled "DUT" (Device Under Test) and "Compliment of DUT (N-Channel)". The drain-source voltage is V_{DS} and the drain-source current is I_{SD} . The driver is an N-channel MOSFET. The circuit is designed to control dv/dt via R_G and I_{SD} via the pulse period.

The bottom part of the image shows three waveforms corresponding to the circuit operation:

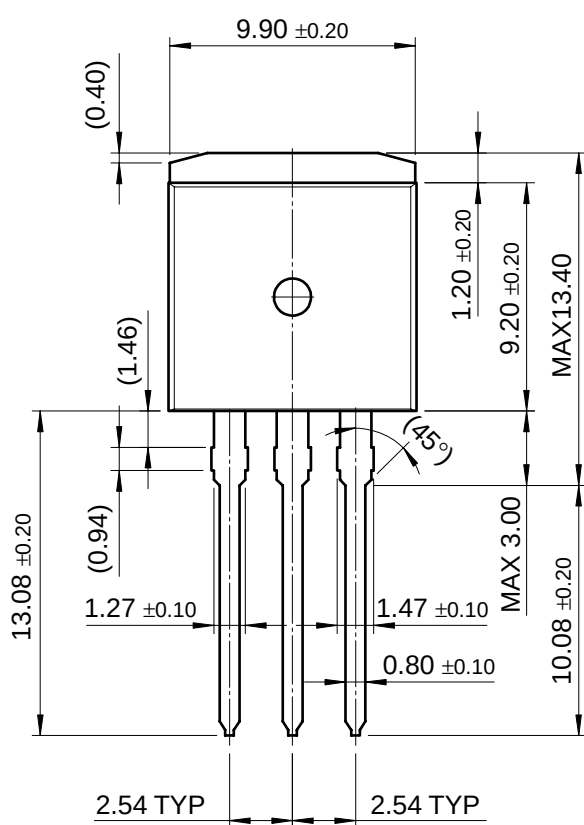
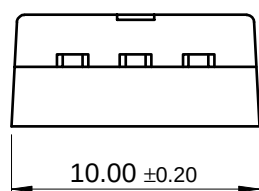
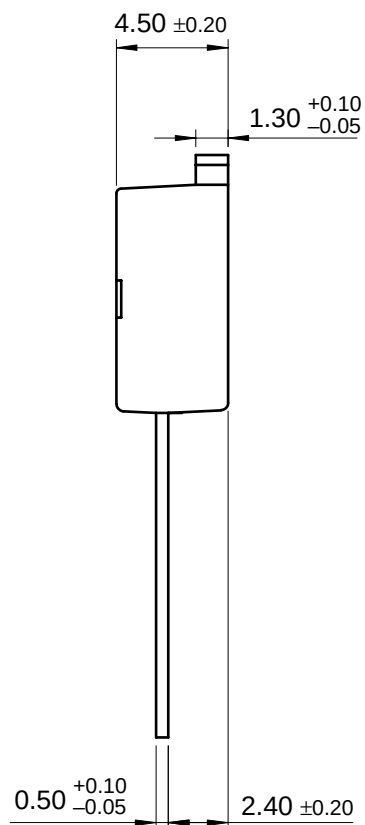
- V_{GS} (Driver):** A square wave pulse. The duty cycle is defined as $D = \frac{\text{Gate Pulse Width}}{\text{Gate Pulse Period}}$. The pulse height is 10V.
- I_{SD} (DUT):** The drain-source current. It shows a negative "Body Diode Reverse Current" I_{RM} during the gate pulse and a positive "Body Diode Forward Current" I_{FM} during the off-time. The di/dt is indicated on the rising edge.
- V_{DS} (DUT):** The drain-source voltage. It shows a "Body Diode Forward Voltage Drop" during the on-time and a "Body Diode Recovery dv/dt " during the off-time. The supply voltage V_{DD} is indicated.

Package Dimensions

D²PAK

FQB11P06 / FQI11P06

Package Dimensions (Continued)

I²PAK

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